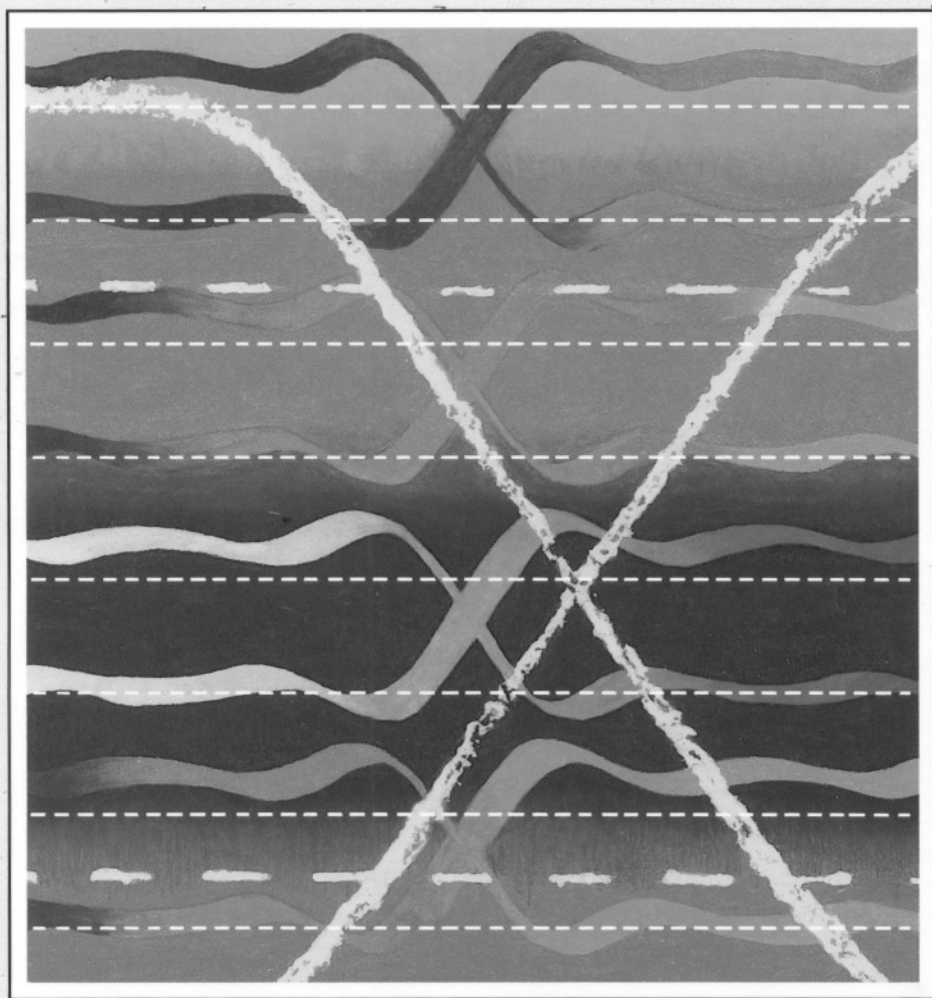


HIGH-SPEED DIGITAL DESIGN

A HANDBOOK OF BLACK MAGIC



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HIGH-SPEED DIGITAL DESIGN

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